



TP11 and TP12 are for scope voltage probe
 TP9 and TP10 are for Vout regulation and efficiency

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|-----------------------------------|----------------------------------------------------------------------------|---------------------|
| Orderable: EVM_orderable | Designed for: Public Release | Mod. Date: 3/2/2017 |
| TID #: PMP20050 | Project Title: SWIFT | |
| Number: PMP20050 | Rev: E1 | Sheet Title: |
| SVN Rev: Version control disabled | Assembly Variant: [No Variations] | Sheet: 1 of 2 |
| Drawn By: | File: PMP20050.SchDoc | Size: B |
| Engineer: M Battan / R Taylor | Contact: http://www.ti.com/support | |

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PCB Number: PMP20050
PCB Rev: E1

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You should delete the nylon screws/standoffs and/or the bumpers as needed for your design (or substitute other parts from Hardware.IntLib). Bumpers are cheaper, but provide less clearance.

Deleting anything else from this page may result in your EVM submission being rejected (until you add them back).

Update the Label Text in the Label Table as needed for each Assembly Variant.

You can delete this note too.

| Label Table | |
|-------------|------------|
| Variant | Label Text |
| 001 | ChangeMe! |
| 002 | ChangeMe! |
| | |
| | |
| | |
| | |
| | |

ZZ2

Assembly Note

These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3

Assembly Note

These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4

Assembly Note

These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

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